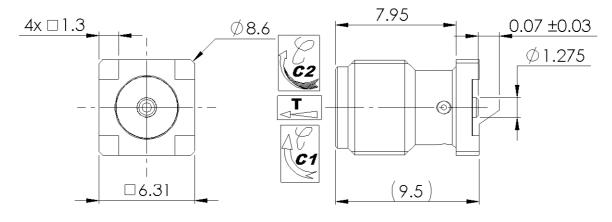
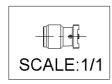
R124.427.000

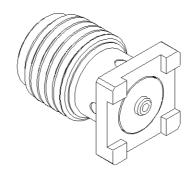
Series: SMA-COM

4 indents captivation c. contact (Tenue c. central par 4 creves)

*set back of c. contact from body (Retrait du c. contral/ au corps)







All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	BRASS BERYLLIUM COPPER - PTFE	GOLD OVER NICKEL GOLD OVER NICKEL

Issue: 1138 B

In the effort to improve our products, we reserve the right to make changes judged to be



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PACKAGING

Standard Unit Other 100 'W' option Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance **50** Ω **0-18** GHz

Frequency

VSWR 1.04 + **0.0450** x F(GHz) Maxi

Insertion loss **0.05** $\sqrt{F(GHz)}$ dB Maxi **100** - F(GHz)) dB Maxi

RF leakage Voltage rating 500 Veff Maxi

Dielectric withstanding voltage 1000 Veff mini Insulation resistance **5000** MΩ mini

ENVIRONMENTAL

-65/+165 ° C Operating temperature

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHER CHARACTERISTICS

Assembly instruction

Others:

FORCE F1:100N-TORQUES C1:70Ncm-C2:90Ncm

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end 15 N mini Axial force – Opposite end 15 N mini Torque 1 N.cm mini

Recommended torque

Mating - N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

1,1000 g Weight

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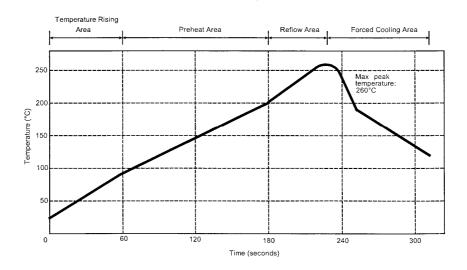
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SOLDER PROCEDURE

- 1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 microns mini (.006 inch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Aspiration port centered into body and push against it.
 - Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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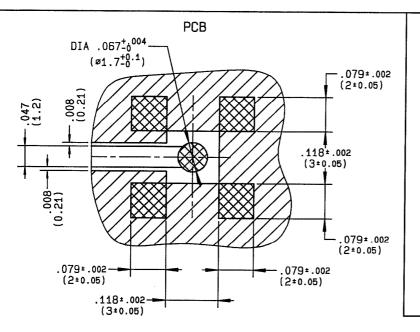
necessary.

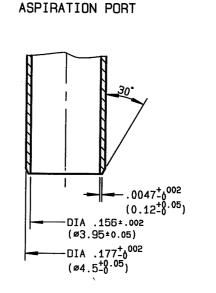


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Series: SMA-COM

SMA B SERIES - INFORMATIONS





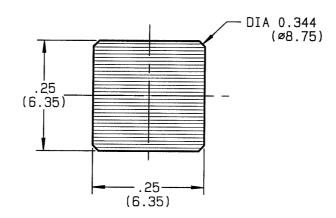
COPLANAR LINE

Pattern and signal are on the same side Thickness of PCB: .063 (1.6 mm)
The material of PCB is the epoxy resin of glass fabrics bacs.(Er = 4.8)
The solder resist should be printed exept for the land pattern on the PCB.

Pattern

Land for solder paste

SHADOW OF "SMA B" RECEPTACLE FOR VIDEO CAMERA



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